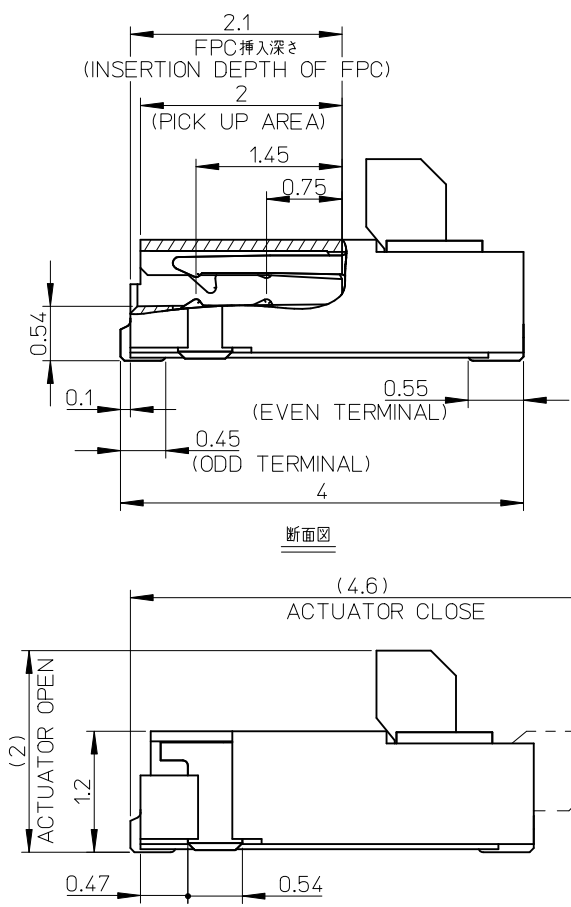
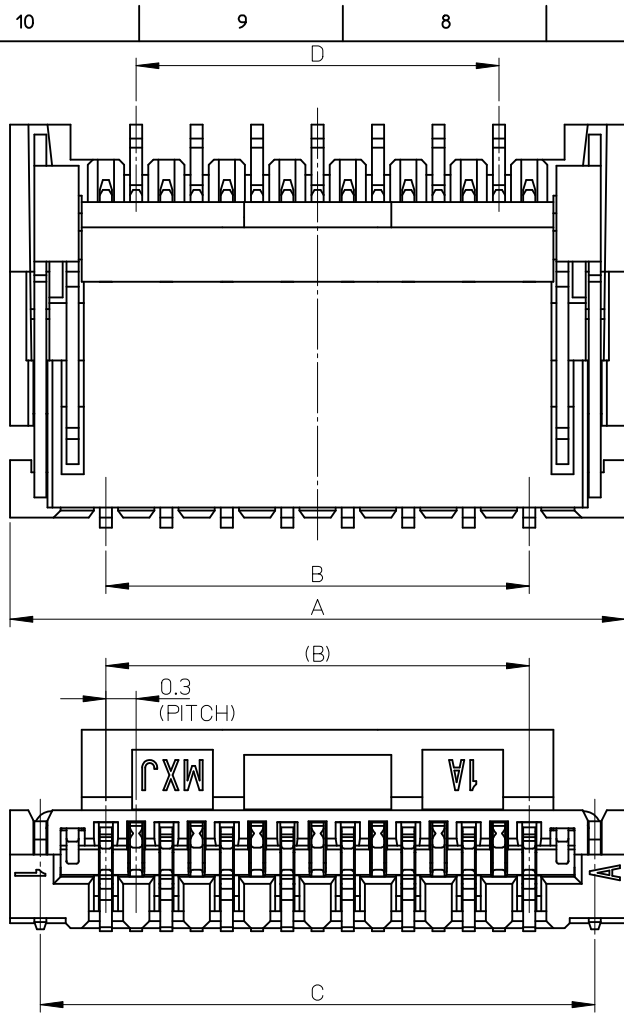




注記
NOTES:

- 1.材質
MATERIAL
ハウジング:液晶ポリマー(LCP)、ナチュラル(白)、ガラス充填、UL94V-0
HOUSING:LIQUID CRYSTAL POLYMER(LCP),NATURAL(WHITE)
GLASS FILLED,UL94V-0
アクチュエータ:ポリフェニレンサルファイド(PPS)、黒色、ガラス充填、UL94V-0
ACTUATOR:POLYPHENYLENE SULFIDE(PPS),BLACK
GLASS FILLED,UL94V-0
ターミナル:銅合金(t=0.12)
TERMINAL:COPPER ALLOY(t=0.12)
金具:リン青銅(t=0.12)
NAIL:PHOS-BRO(t=0.12)
- 2.めっき仕様
PLATING
ターミナル
TERMINAL
接点部:金めっき 0.1μm以上
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM.
半田付け部:金めっき
SOLDER TAIL AREA: GOLD
下地めっき:ニッケル 1.0μm以上
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM.
金具
NAIL
銅めっき 1.0μm以上
TIN PLATING 1.0 MICROMETER MINIMUM.
下地めっき:ニッケル 1.0μm以上
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM.
- 3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.
- 4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

0.208	21.6	23.5	22.2	24.1	503425-7591	75
0.171	17.4	19.3	18.0	19.9	503425-6191	61
重さ (g)	D	C	B	A	EMBOSSED PACKAGE	極 数
WEIGHT(g)					オーダー番号 ORDER NO.	CIRCUITS

CONNECTOR SERIES No. 503425-**11

RELEASED EC NO: J2010-2422 2009/04/28 DRWN:KUSATO 2010/05/28 CHKD:HSHIMOYAMA 2010/05/31 APPR:KMORI KAWA	DESCRIPTION REV 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY KUSATO	DATE 2008 / 11 / 14	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY				
		10 OVER 30 UNDER	± 0.25	CHECKED BY HSHIMOYAMA	DATE 2008 / 11 / 14					
		30 OVER	± 0.3	APPROVED BY HHIRATA	DATE 2008 / 11 / 14					
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-503425-001		1 OF 2		
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

F

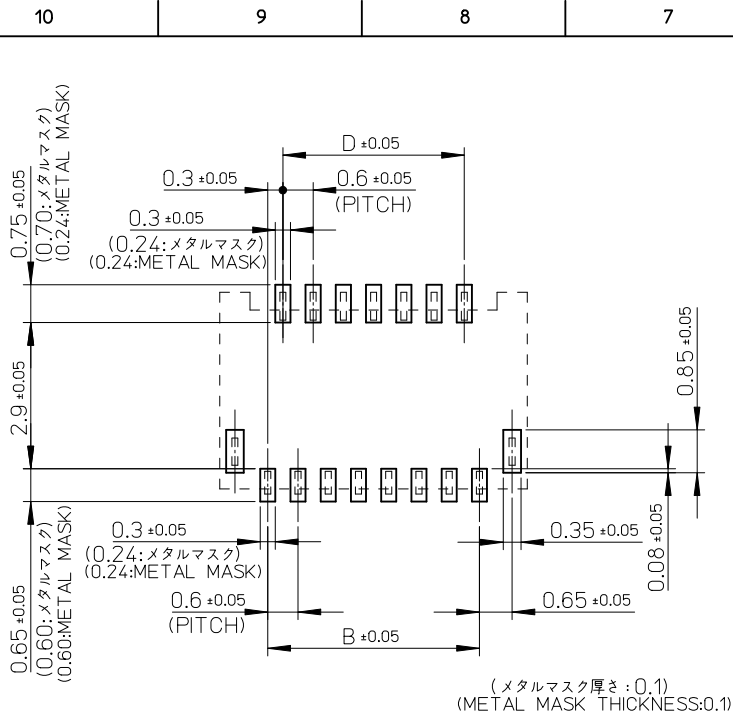
E

D

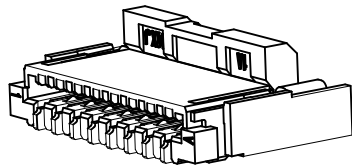
C

B

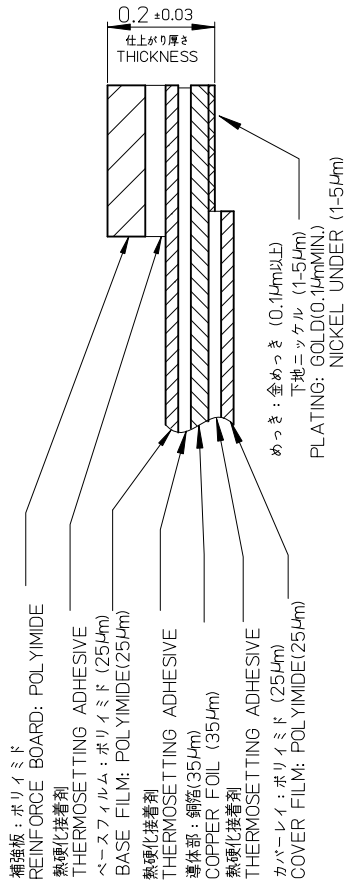
A



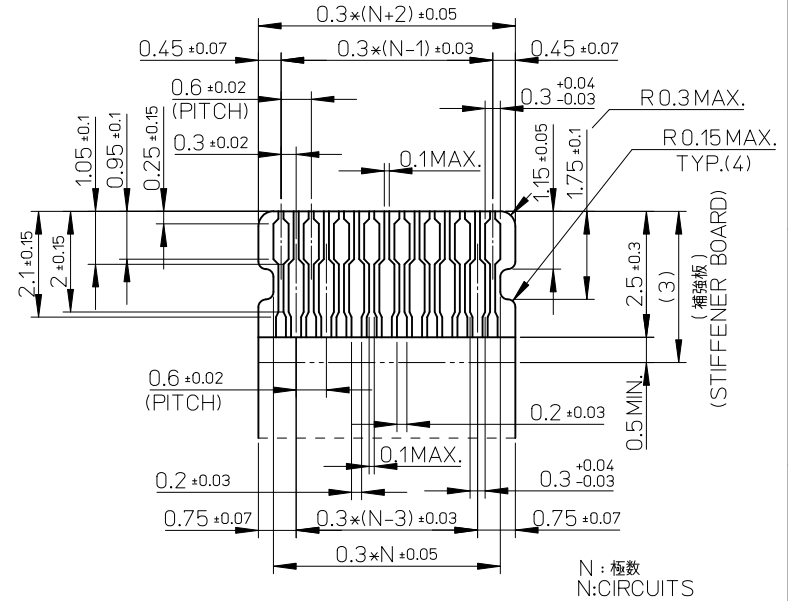
推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT



ISO VIEW (参考)



FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ±0.03)
(THICKNESS: 0.2 ±0.03)

FPCについて:

抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:

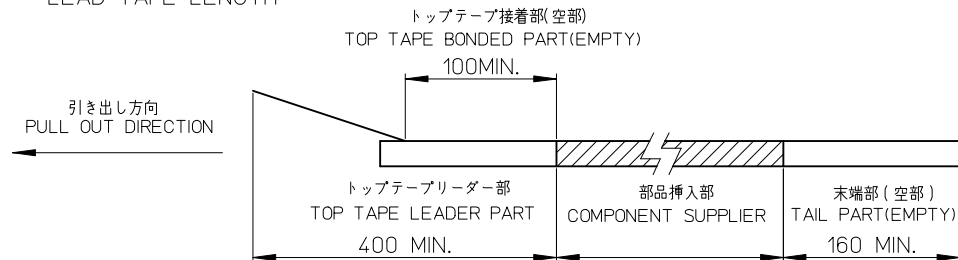
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.

RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

SEE SHEET 1 EC NO: J2010-2422 DRWN:KUSATO 2009/04/28 CHKD:SHIMOYAMA 2010/05/28 APPR:KMORIKAWA 2010/05/31	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY KUSATO	DATE 2008/11/14	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY			
		10 OVER 30 UNDER	± 0.25	CHECKED BY HSHIMOYAMA	DATE 2008/11/14				
		30 OVER	± 0.3	APPROVED BY HHIRATA	DATE 2008/11/14	 MOLEX INCORPORATED			
		ANGULAR ±1 °		MATERIAL NO.					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-503425-001		2 OF 2		
	REV 0	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

注記)
NOTES

- 製品番号503425-**11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 503425-**11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量:3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

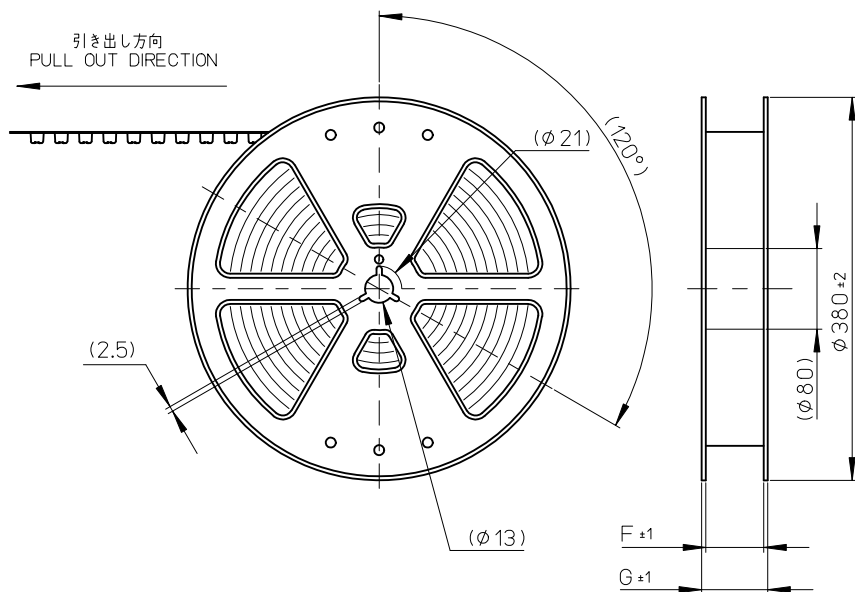
5.材料

MATERIAL

キャリアテープ:ポリスチレン(PS)
CARRIER TAPE:POLYSTYRENE(PS)
トッテープ:PET、PE、PEF
TOP TAPE :PET、PE、PEF
リール:ポリスチレン
REEL:POLYSTYLENE

6.ELV及びRoHS適合品

ELV AND LoHS COMPLIANT



RELEASED EC NO: J2010-2422 2008/11/19 DRWN:KUSATO 2010/05/28 CHKD:HSHIMOYAMA APPR:KMORIKAWA 2010/05/31	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY KUSATO	DATE 2008/11/19	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (503425-**11 SERIES)			
		10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2008/11/19				
		30 OVER	± ---	APPROVED BY HHIRATA	DATE 2008/11/19	 MOLEX INCORPORATED			
		ANGULAR ±1 °		MATERIAL NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1 OF 2		SD-503425-002		1 OF 2	
	REV 0	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

